G. Ramanath et al.

Application No.: 09/976,927

Page 2

CI

28. (New) The semiconductor device of claim 24 wherein the metal layer is in direct contact with the diffusion barrier layer.

## REMARKS

This Supplemental Amendment supplements the Amendment filed on November 21, 2002, and is responsive to the Office Action mailed on July 22, 2002. Claim 28 is added so that claims 13-28 are now pending and subject to examination.

Also attached is a Declaration of Shyam Murarka Pursuant to 37 C.F.R. § 1.132. The Examiner is requested to consider the Declaration as evidence supporting Applicants' arguments in the November 21, 2002 Amendment that embodiments of the invention are not inherently disclosed in U.S. Patent Nos. 6,079,600 (Schnur '600) and 5,389,496 (Calvert '496). In view of the Declaration and Applicants' arguments in the November 21, 2002 Amendment, the Examiner is requested to withdraw the pending prior art rejections.

## **CONCLUSION**

The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 415-576-0200.

Respectfully submitted,

Patrick R. Jewik Reg. No. 40,456

TOWNSEND and TOWNSEND and CREW LLP Two Embarcadero Center, 8<sup>th</sup> Floor San Francisco, California 94111-3834

Tel: 415-576-0200 Fax: 415-576-0300

PRJ SF 1418436 v1